	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
1	BRS	222015	die or wafer or semiconductor or (circuit near2 board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 12:43		
2	BRS	31247	(die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 12:45		
3	BRS	5108	((die or wafer or semiconductor or (circuit near2 board)) near7 ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6))) same imag$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:28		
4	BRS	4	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6)))) same imag$3) and 382/284.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 12:51		
5	BRS	162	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6)))) same imag$3) and ((imag$3 near5 (partial or portion or section or tile or block)) same (imag$3 near5 (composite or whole or entire)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 12:59		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
6 BRS	57	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6))) same imag$3) and ((imag$3 near5 (partial or portion or section or tile or block)) same (imag$3 near5 (composite or whole or entire)))) and @rlad<20010925	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:10		
7 BRS	166	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6))) same imag$3) and ((imag$3 near5 (partial or portion or section or tile or block)) same (imag$3 near5 (composite or whole or entire or mosaic)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 17:15		
8 BRS	2	6684379.pn. and (tile or mosaic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 13:33		
9 BRS	0	6684379.pn. and (defect$3 or fault$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 13:33		
10 BRS	1	6172365.pn. and thick$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 16:59		
11 BRS	1	6684379.pn. and (camera or imager or imaging or ccd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:08		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
12 BRS	5108	((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6)))) same imag$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 17:05		
13 BRS	543	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6))) same imag$3) and (((two adj dimension$4) or "2-d" or ("2" adj dimension$4) or "2" near5 (sensor or (imag$3 near2 device) or camera or CCD))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 17:12		
14 BRS	143	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6))) same imag$3) same ((two adj dimension$4) or "2-d" or ("2" adj dimension$4) or array) near5 (sensor or (imag$3 near2 device) or camera or CCD))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/21 17:15		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
15 BRS	41	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6))) same imag$3) same (((two adj dimension$4) or ("2-d" or ("2" adj dimension$4) or array) near5 (sensor or (imag$3 near2 device) or camera or CCD))) and @rlad<2001925	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:30		
16 BRS	1	6684379.pn. and zoom$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 17:50		
17 BRS	1	6753518.pn. and height	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:10		
18 BRS	5108	((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6)))) same imag$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 20:40		
19 BRS	152070	(die or wafer or semiconductor or (circuit near2 board)) near7 (thick$4 or width or height)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:29		
20 BRS	851	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6)))) and ((die or wafer or semiconductor or (circuit near2 board)) near7 (thick$4 or width or height))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:29		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
21	BRS	2614	(die or wafer or semiconductor or (circuit near2 board)) near7 (thick$4 or width or height) near7 (distribut$5 or histogram or map$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:30		
22	BRS	9687	(die or wafer or semiconductor or (circuit near2 board) or film) near7 (thick$4 or width or height) near7 (distribut$5 or histogram or map$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:30		
23	BRS	86	((((die or wafer or semiconductor or (circuit near2 board)) near7 ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or analy$9 or determin$6))) same imag$3) and ((die or wafer or semiconductor or (circuit near2 board) or film) near7 (thick$4 or width or height) near7 (distribut$5 or histogram or map$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:30		
24	BRS	40	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or ((defect$3 or fault$3) near4 (detect$4 or recongi$8 or determin$6)))) same imag$3) and ((die or wafer or semiconductor or (circuit near2 board) or film) near7 (thick$4 or width or height) near7 (distribut$5 or histogram or map$4)) and @rlad<20010925	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 20:45		
25	BRS	1	"200306 2479" and height	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:38		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
26 BRS	1	"20030045131" and (film near3 thick$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 18:38		

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1 BRS	L1	371	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or (defect$3 or fault$3) near4 (detect$4 or recongi$8 or analys9 or determin$6))) same imag$3) and (film near5 (thick$4 or width or height))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/09/2 20:44			0
2 BRS	L2	1	6684379.pn. and film	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/09/2 20:43			0
3 BRS	L3	27	(((die or wafer or semiconductor or (circuit near2 board) near7 (inspect$4 or (defect$3 or fault$3) near4 (detect$4 or recongi$8 or analys9 or determin$6))) same imag$3) and (film near5 (thick$4 or width or height) with (distribut$4 or map$5))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/09/2 21:14			0

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
BRS	L4	11	3 and @rlad<20010925	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/09/2 2 21:16			0
BRS	L5	19	(((die or wafer or semiconductor or (circuit near2 board)) near7 (inspect$4 or (defect$3 or fault$3) near4 (detect$4 or recongi$8 or analys9 or determin$6))) same imag$3) and (film near5 (thick$4 or width or height) near5 (point or location))	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB	2004/09/2 2 21:16			0
BRS	L6	5	5 and @rlad<20010925	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB				0